



Q2 FY2026 Financial Announcement

April 2026 –
June 2026

August 10, 2026

Security Code:
6266

Company Guide



INDEX



1. **Q2 FY2026 Consolidated Financial Summary**
2. **Q2 FY2026 Segment Information**
3. **Business Environment**
4. **Appendix**



1

Q2 FY2026 Consolidated Financial Summary

Net sales

12,684

Million Yen

YoY Change $\triangle 24.4\%$

Operating income

123

Million Yen

YoY Change $\triangle 95.1\%$

Ordinary income

270

Million Yen

YoY Change $\triangle 88.6\%$

Net income(*)

35

Million Yen

YoY Change $\triangle 97.8\%$

■ Overview

- Both sales and profit declined year on year. Net sales fell short of the plan in the Semiconductor Equipment, Transfer Equipment and Surface Treatment Equipment Businesses.
- Profit also fell well short of the plan, reflecting the lower net sales, valuation losses on equipment not yet inspected and accepted, and provisions for additional costs identified on certain equipment.
- Order intake grew substantially in the Semiconductor Equipment, Transfer Equipment and Surface Treatment Equipment Businesses, marking record highs on both a quarterly and a cumulative basis.

(*) Net income: Net income attributable to owners of parent

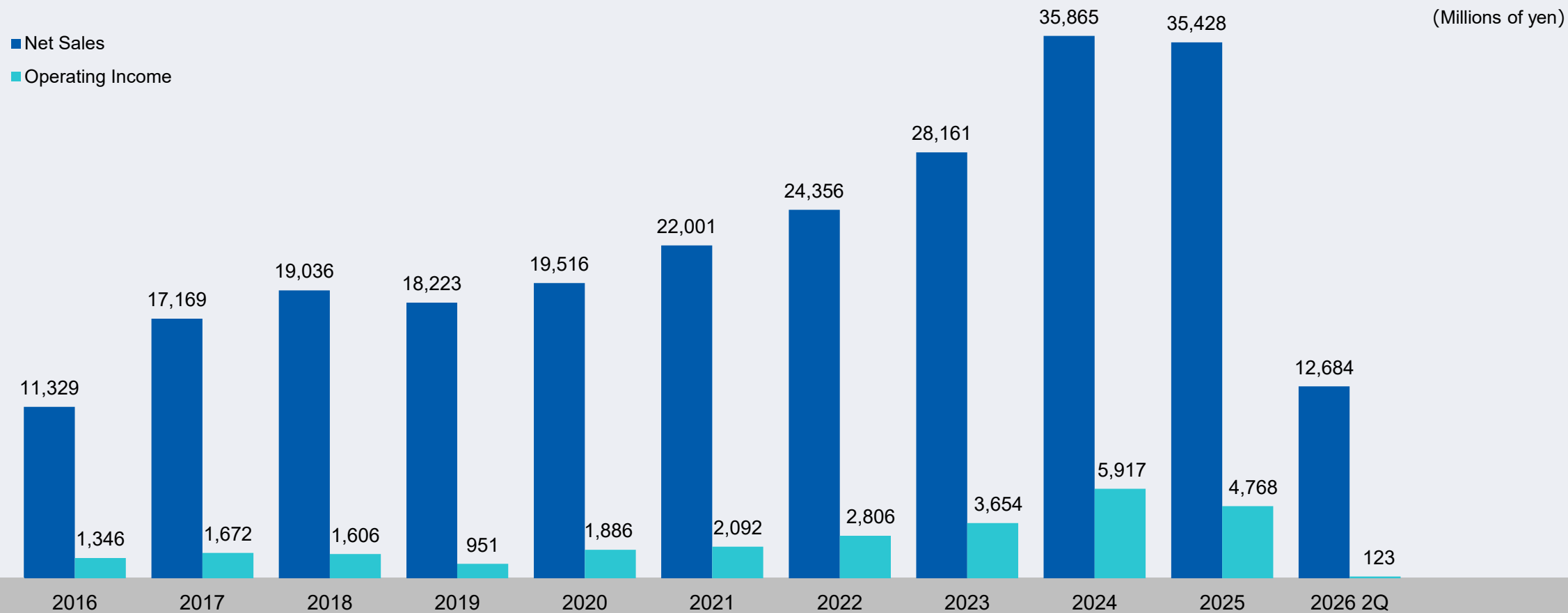
Net sales fell short of the plan, mainly due to delays in inspection and acceptance in the Semiconductor Equipment and Surface Treatment Equipment Businesses. Profit also fell well short of the plan, reflecting the lower net sales, valuation losses on equipment not yet inspected and accepted, and the recognition of additional costs.

(Millions of yen)	Q2 FY2025 Actual	Q2 FY2026		YoY change (%)	FY2026 Initial H1 Estimate	vs. Initial H1 Estimate (%)	FY2026 Full Year Estimate	vs. Full Year Estimate (%)
		Actual	Net sales ratio (%)					
Net sales	16,787	12,684	-	△24.4	15,570	81.5	35,500	35.7
Gross profit	5,231	3,598	28.4	△31.2	-	-	-	-
Operating income	2,517	123	1.0	△95.1	890	13.8	3,600	3.4
Ordinary income	2,384	270	2.1	△88.6	800	33.9	3,500	7.7
Net income attributable to owners of parent	1,645	35	0.3	△97.8	600	6.0	2,500	1.4

Trend in Net sales and Operating profit(Quarterly)



Trend in Net sales and Operating profit (Full year)



(Millions of yen)	FY2025 Actual	Q2 FY2026 Actual	YoY change
Current assets	37,809	38,383	573
Non-current assets	9,083	10,136	1,053
Property, plant and equipment	7,812	8,876	1,063
Intangible assets	199	193	△5
Investments and other assets	1,070	1,066	△4
Total assets	46,893	48,520	1,626
Current Liabilities	14,393	15,892	1,499
Non-Current Liabilities	5,462	5,720	257
Total liabilities	19,855	21,612	1,757
Total net assets	27,037	26,907	△130
Equity ratio	56.6%	54.4%	△2.2P

Major Change

(Millions of yen)

Current Assets

Cash and deposits	△1,498
Notes and accounts receivable - trade	+397
Inventories	+1,545

Current Liabilities

Notes and accounts payable - trade	+888
Electronically recorded obligations – operating	△1,478
Contract liabilities	+2,557
Short-term borrowings	+321
Income taxes payable	△676

Non-Current Liabilities

Long-term borrowings	+207
----------------------	------

(Millions of yen)	Q2 FY2025 Actual	Q2 FY2026 Actual	YoY change(%)
Cash flow from operating activities	4,394	△336	△4,730
Cash flow from investing activities	△4,540	△290	4,249
Free cash flow	△145	△626	△480
Cash flow from financing activities	△556	7	564
Cash on hand	8,719	13,456	4,737

Highlights

(Millions of yen)

Cash flow from operating activities

Profit before income taxes	270
Contract Liabilities	2,401
Inventories	△1,676
Income taxes paid	△826

Cash flow from investing activities

Net increase in time deposits	1,056
Purchase of property, plant and equipment	△1,327

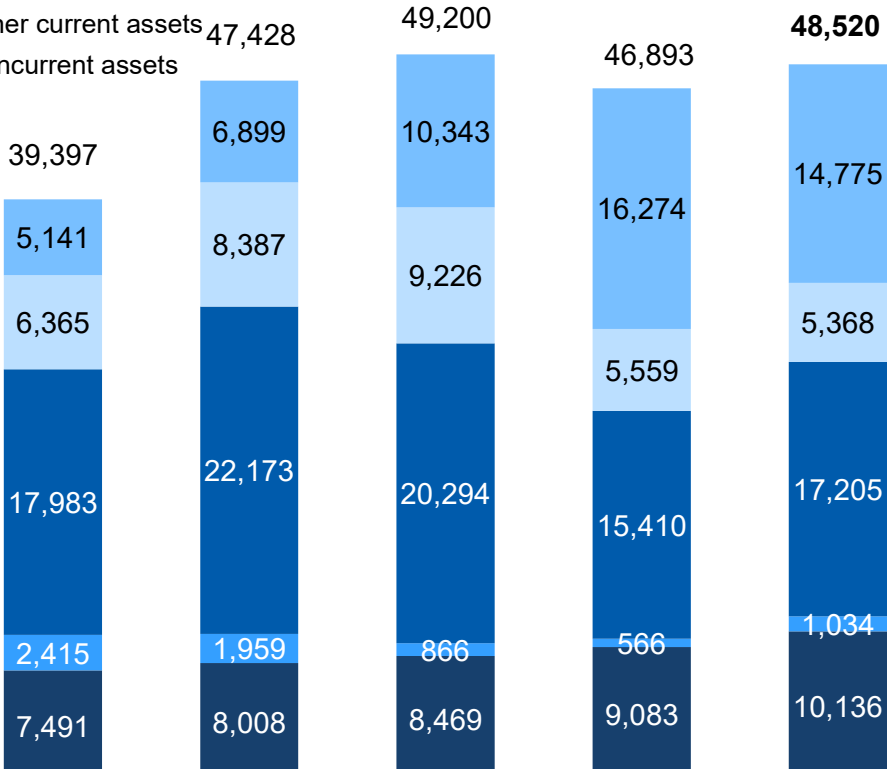
Cash flow from financing activities

Proceeds from long-term borrowings	2,000
Repayments of long-term borrowings	△1,640
Dividends paid	△497

Assets

(Millions of yen)

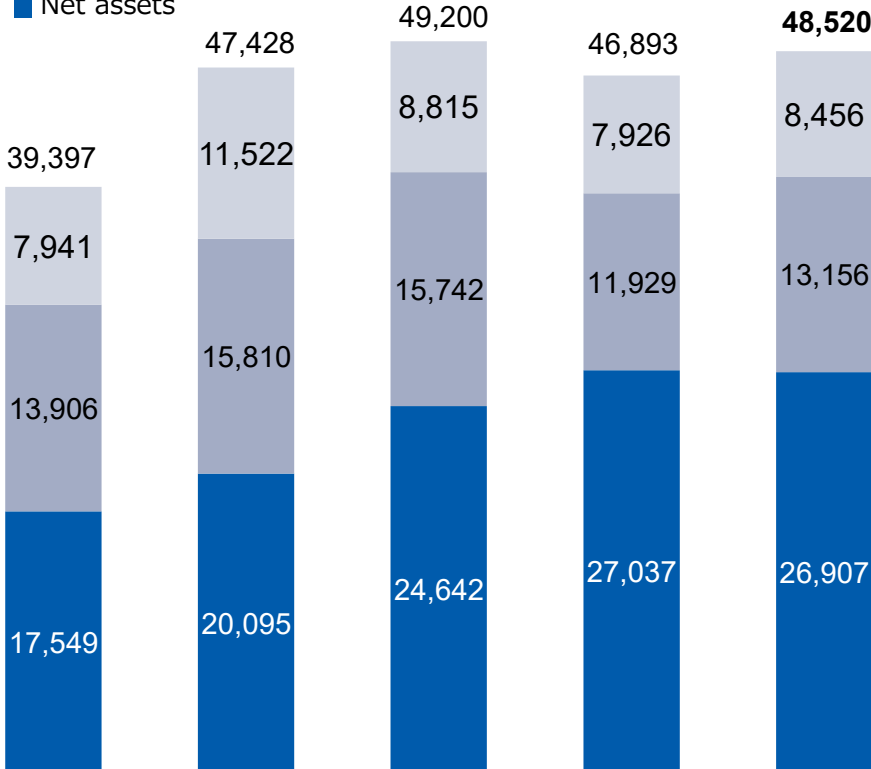
- Cash equivalent
- Trade receivable
- Investors
- Other current assets
- Noncurrent assets



Liabilities/Equity

(Millions of yen)

- Interest-bearing debt
- Other liabilities
- Net assets





2

Q2 FY2026 Segment Information

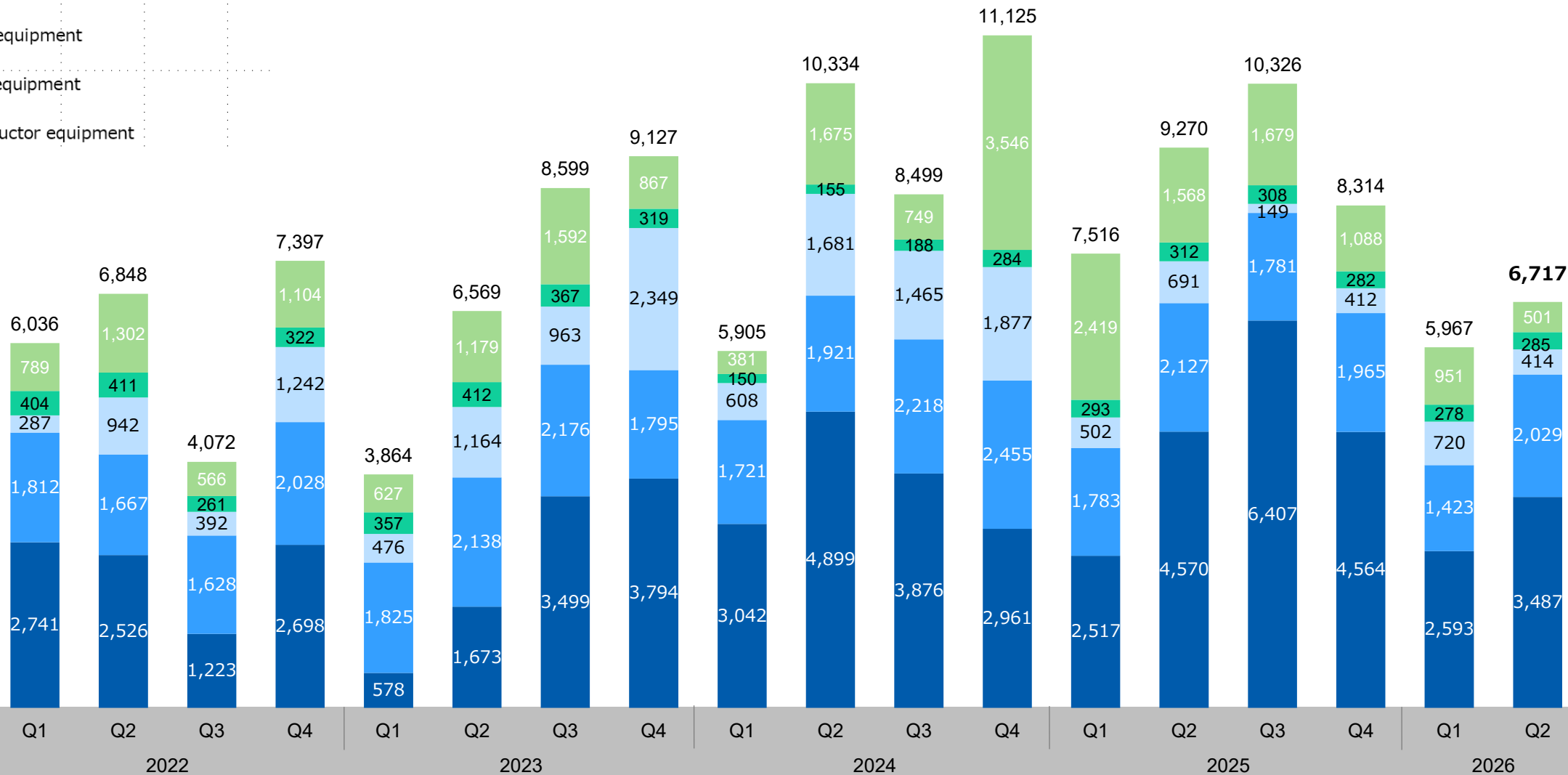
→ Net Sales and Operating Profit by Segment

(Millions of yen)		Q2 FY2025 Actual	Q2 FY2026 Actual	YoY(%)	FY2026 Initial H1 Estimate	vs. Initial H1 Estimate (%)	FY2026 Full Year Estimate	vs. Full Year Estimate (%)
Process equipment business	Net sales	12,193	10,668	△12.5	12,870	82.9	29,700	35.9
	Operating income	1,920	220	△88.5	900	24.5	3,400	6.5
■ Semiconductor equipment	Net sales	7,088	6,080	△14.2	-	-	18,500	32.9
■ Transfer equipment	Net sales	3,911	3,452	△11.7	-	-	8,860	39.0
■ Cleaning equipment	Net sales	1,194	1,135	△4.9	-	-	2,340	48.5
Precision molding dies and plastic moldings business	Net sales	606	563	△7.0	600	94.0	1,300	43.4
	Operating income	56	△2	-	30	-	70	-
Surface treatment equipment business	Net sales	3,987	1,452	△63.6	2,100	69.2	4,500	32.3
	Operating income	517	△89	-	△40	-	130	-
Elimination of inter- segment transactions	Operating income	24	△5	-	-	-	-	-
Total	Net sales	16,787	12,684	△24.4	15,570	81.5	35,500	35.7
	Operating income	2,517	123	△95.1	890	13.8	3,600	3.4

Trend in Net sales by Segment(Quarterly)

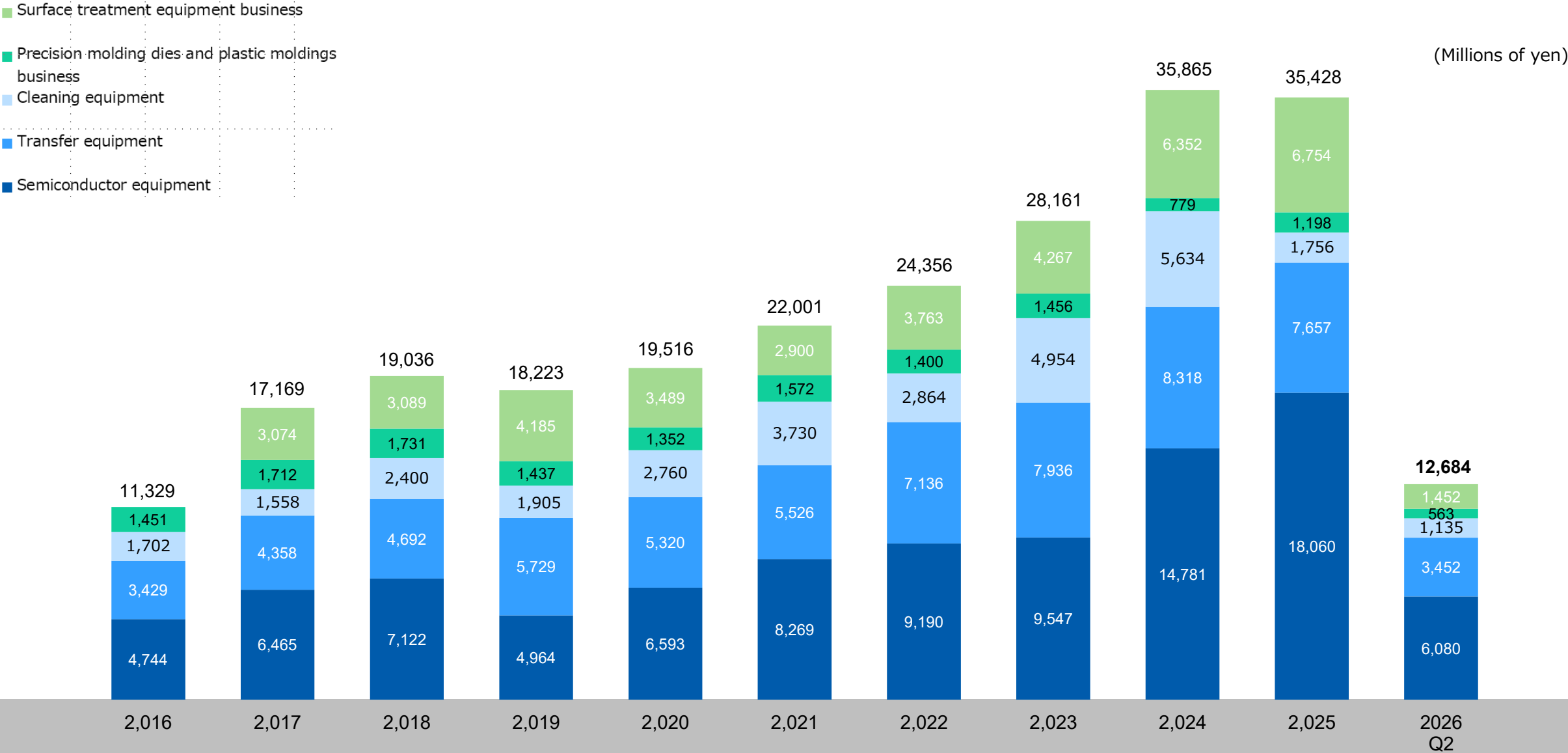
- Surface treatment equipment business
- Precision molding dies and plastic moldings business
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment

(Millions of yen)



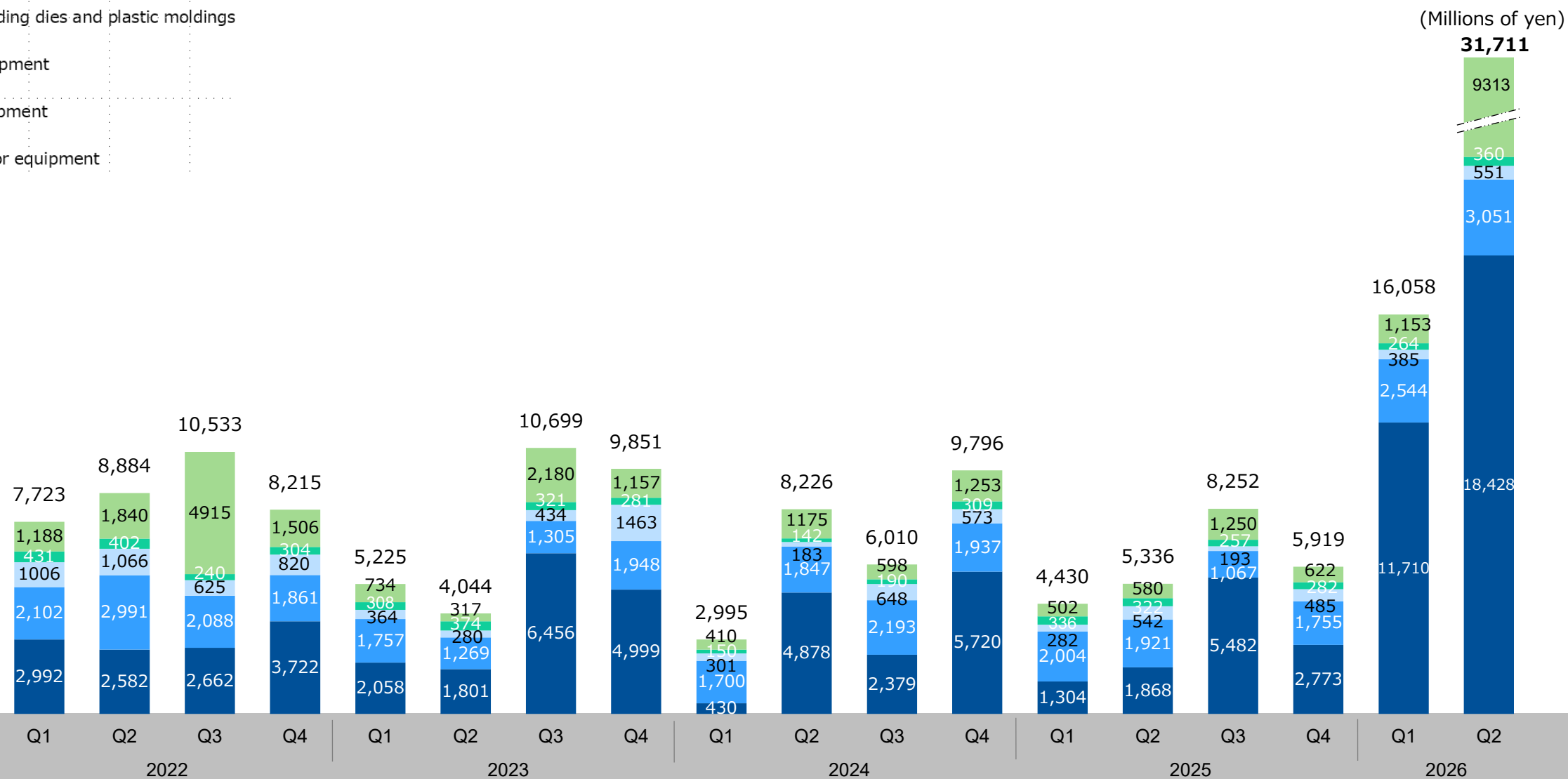
Starting from the fiscal year ending December 2026, the business previously recorded under the "Coater" segment has been reclassified and reported in combination with the "Semiconductor Equipment" segment. Accordingly, past performance figures have also been restated under the same segment classification. For sales trends under the previous classification, please refer to the supplementary materials.

Trend in Net sales by Segment(Full year)



Trend in Sales Orders by Segment(Quarterly)

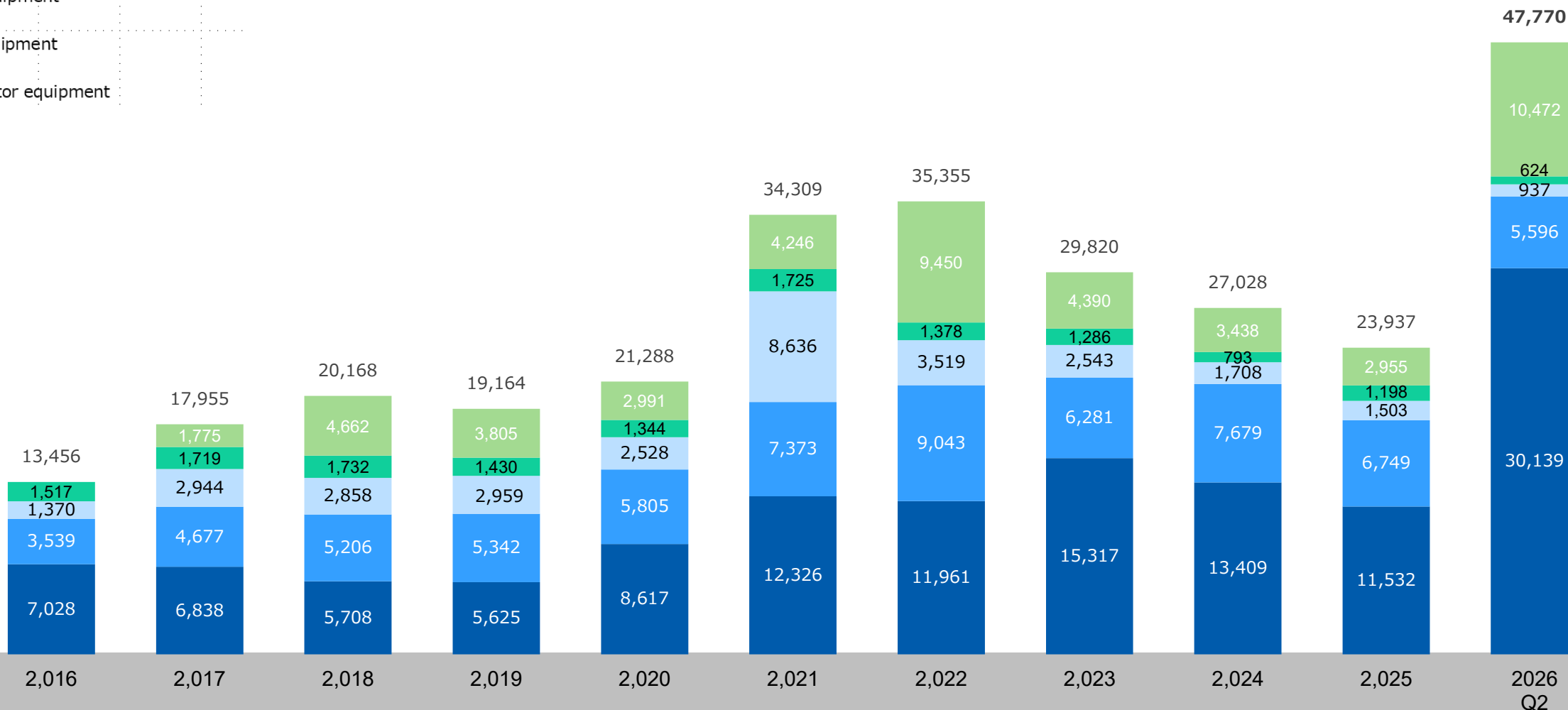
- Surface treatment equipment business
- Precision molding dies and plastic moldings business
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment



Trend in Sales Orders by Segment(Full year)

- Surface treatment equipment business
- Precision molding dies and plastic moldings business
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment

(Millions of yen)

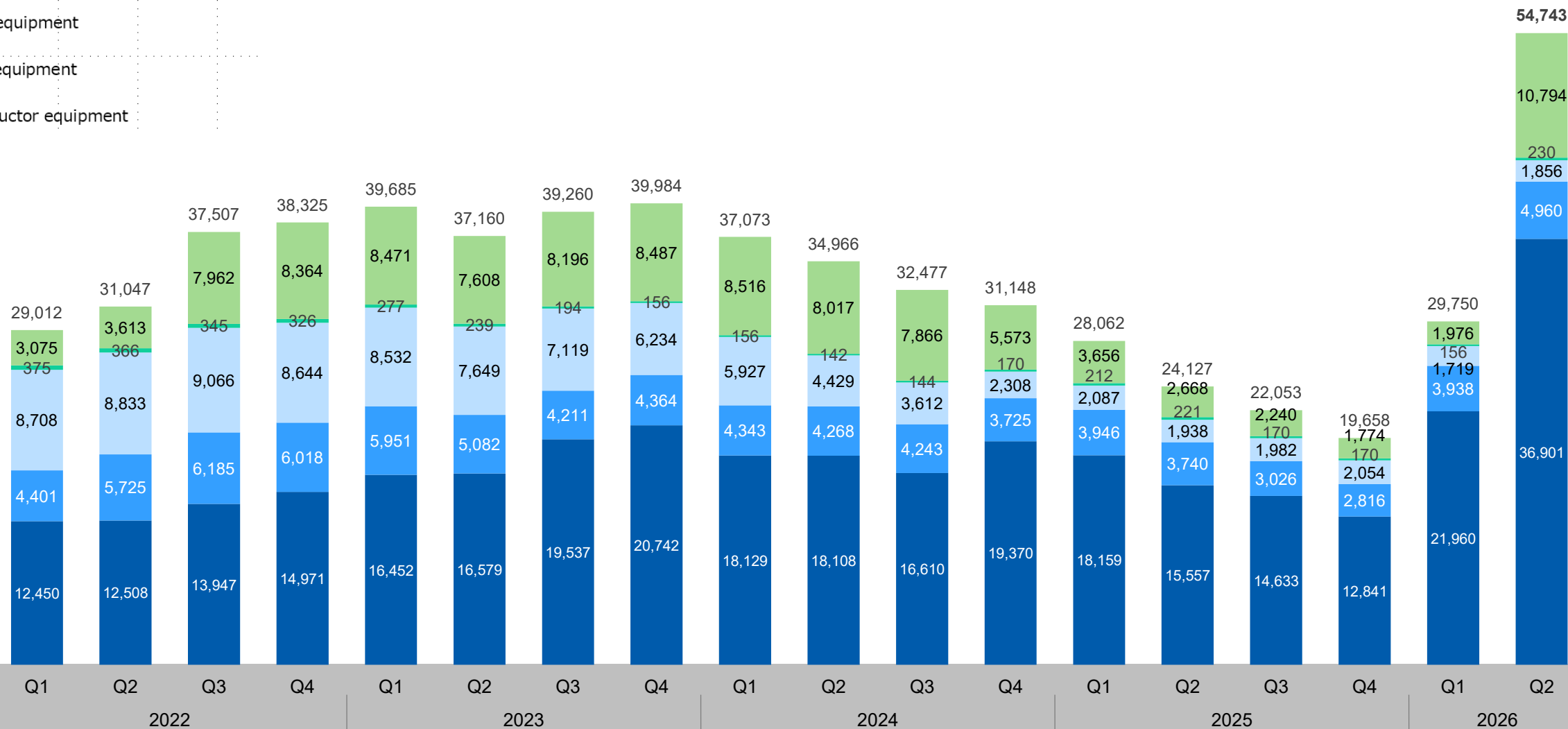


Starting from the fiscal year ending December 2026, the business previously recorded under the "Coater" segment has been reclassified and reported in combination with the "Semiconductor Equipment" segment. Accordingly, past performance figures have also been restated under the same segment classification. For sales trends under the previous classification, please refer to the supplementary materials.

Trend in Order Backlog by Segment(Quarterly)

- Surface treatment equipment business
- Precision molding dies and plastic moldings business
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment

(Millions of yen)



Starting from the fiscal year ending December 2026, the business previously recorded under the "Coater" segment has been reclassified and reported in combination with the "Semiconductor Equipment" segment. Accordingly, past performance figures have also been restated under the same segment classification. For sales trends under the previous classification, please refer to the supplementary materials.



3

Business Environment

- For WLP equipment for advanced packaging, order intake declined quarter on quarter following the large orders received in Q1, while orders for coaters and developers expanded. Future orders will depend largely on market conditions, but we remain optimistic. For equipment for power semiconductors, inquiries are gradually increasing.
- In transfer equipment, inquiries have risen sharply and order intake has increased. Despite challenges such as longer lead times for materials and responding to individual customer requirements, we are strengthening our domestic and overseas supply chains.
- For PLP equipment for advanced packaging, inquiries are increasing for the coating, debonding and cleaning processes we have long worked on. The inquiries vary in scale, and we are working to secure them reliably while expecting further market expansion.
- Inquiries for slurry supply equipment are increasing, and we expect further orders going forward. For wafer cleaning equipment, new projects remain limited and we expect recovery to take time.
- In surface treatment equipment, orders expanded for both wet processing equipment centered on plating and substrate transfer equipment. Given the very strong conditions in this market, we remain optimistic going forward.



4

Appendix

(as of June 30, 2026)

Company name	TAZMO Co., Ltd.
Established	February 26, 1972
Head office	5311, Haga, Kita-ku, Okayama-shi, Okayama 701-1221, Japan
Capital	3,556,890,682 yen
Total number of issued shares	14,842,354
Number of shareholders	6,279
Number of employees	Non-consolidated 481 Consolidated 1,224
Business content	Development, Manufacturing and Sales of Semiconductor Manufacturing Equipment, Clean Transfer System, UV Laser Equipment, Plating Equipment, Mold/Resin Molding, Plating/Circuit formation Equipment for PCB

Domestic locations, Subsidiaries

Okayama-shi, Okayama
Head office

Shinjuku-ku, Tokyo
Tokyo office

Ibara-shi, Okayama
TAZMO Plant No.1
TAZMO Plant No.3
TAZMO Plant No.5
Quark Technology Co., Ltd.
PRETEC Co., Ltd.

Global Network

Dongguan City, Guangdong Province, China
Facility Technology (Dongguan) Co., Ltd.

Taiwan
TAZMO Apprecia Formosa Inc.

Hong Kong
Facility (HK) Co., Ltd.

Shaoxing City, Zhejiang Province, China
TAZMO Semitec Shaoxing Technology Co., Ltd.

San Francisco
TAZMO INC.

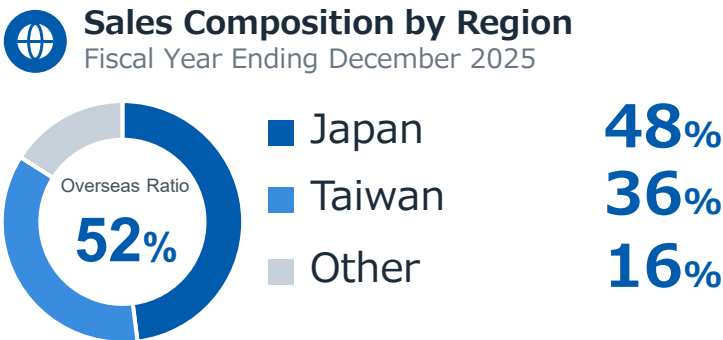
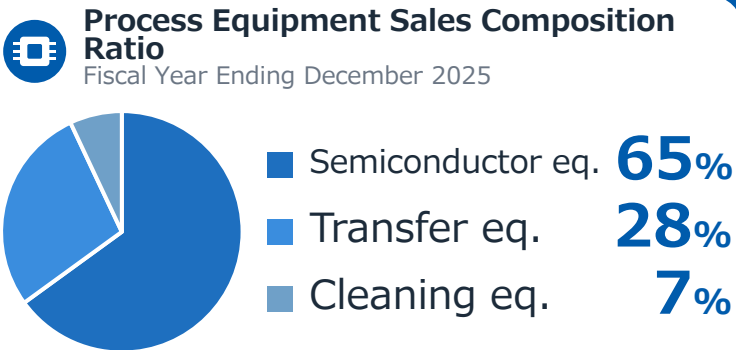
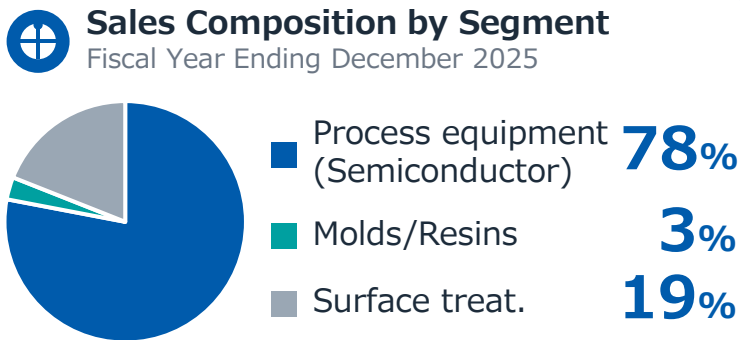
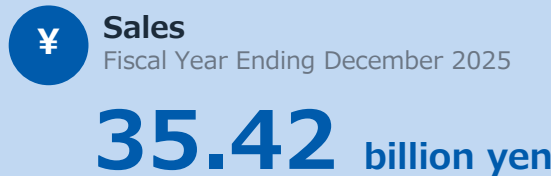
Vietnam
TAZMO VIETNAM CO.,LTD.
FACILITY HANOI CO.,LTD.

Nearly 80% of sales come from semiconductor-related (process equipment business). Overseas sales account for about 52%, making it a global semiconductor equipment manufacturer.

[Company Overview as of 2026]



[Full-Year Results for Fiscal Year Ending December 2025]



In the 1980s, it entered the semiconductor equipment sector. From then on, we flexibly responded to the needs of the times, including FPDs, power semiconductors, and advanced packaging. Currently, we have shifted our sales focus from OEM to direct sales, and we are involved in process development for semiconductor manufacturing.

(1) Founding to the 1990s

Entered the semiconductor equipment business. Accumulated wet process and conveying technology centered on OEMs.

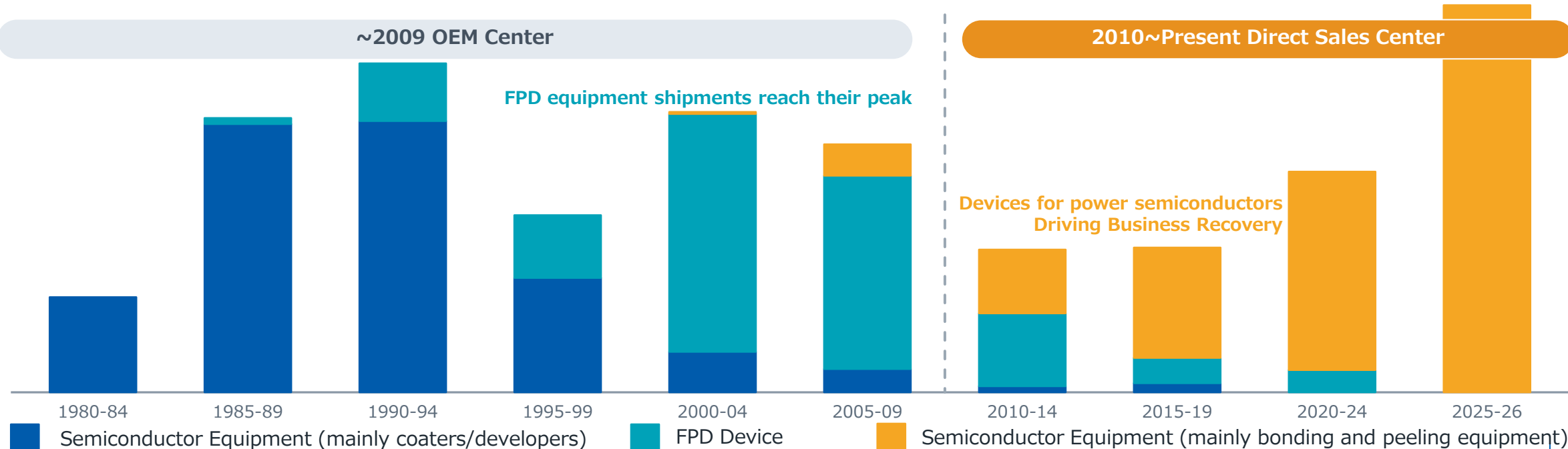
(2) 2000s

FPD equipment (OEM) has become the core of our business. The mid-2000s marked the peak of shipments.

(3) 2010s to Present

From FPDs to semiconductor devices. Expanding into power semiconductors and advanced packaging, sales shifted from OEM to direct sales.

■ Trends in Average Shipments by Period by Main Product Group

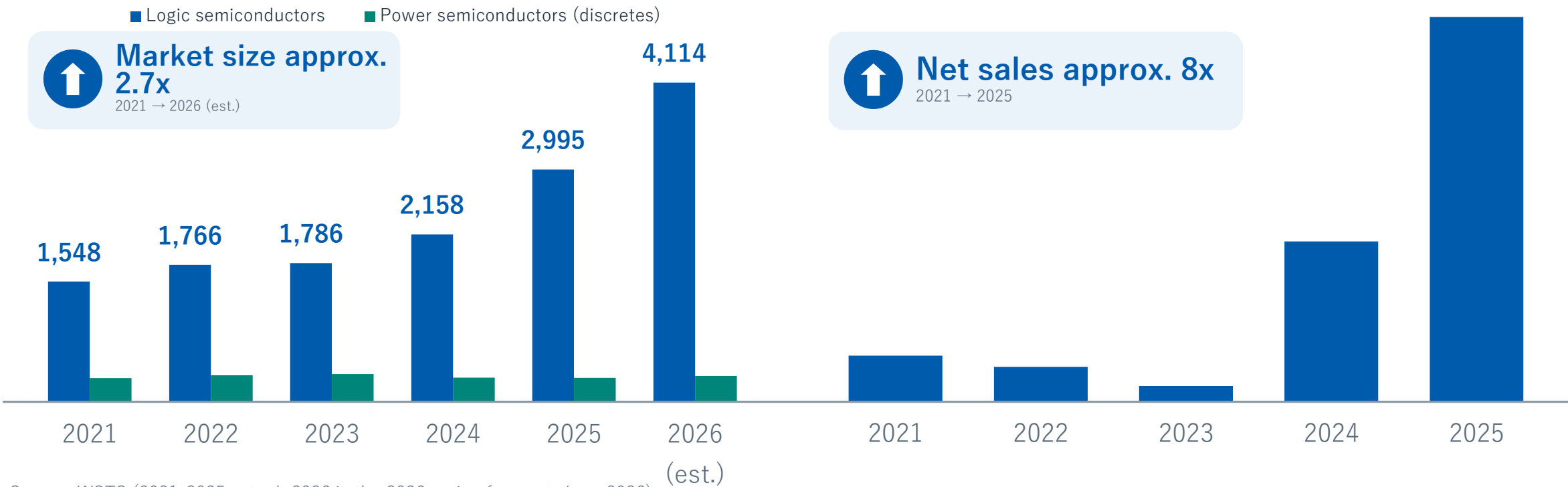


* Shipment numbers for 2025-26 include forecasts for the fiscal year ending December 2026. © 2024 TAZMO Co.,Ltd.

AI-driven expansion of the logic semiconductor market has significantly grown sales of TAZMO's advanced packaging equipment. TAZMO equipment is used in logic semiconductor manufacturing, where technical requirements keep rising.

■ Market size comparison:
logic vs. power semiconductors

■ TAZMO advanced packaging equipment: net sales trend

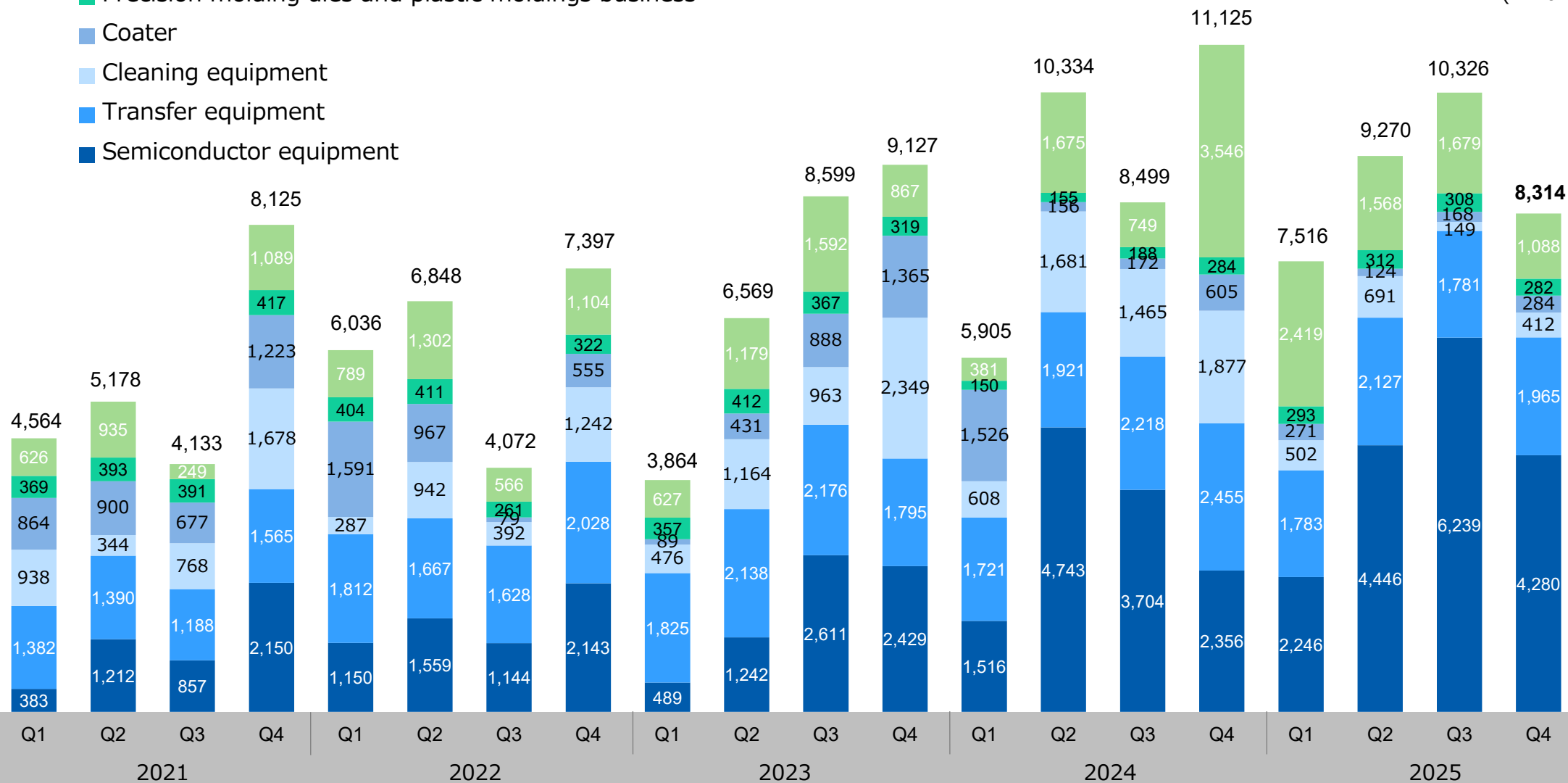


Source: WSTS (2021-2025 actual; 2026 is the 2026 spring forecast, June 2026).
*Discretes is a category centered on power semiconductors.
*Unit: US\$100 million

Trend in Net sales by Conventional Segment(Quarter)

- Surface treatment equipment business
- Precision molding dies and plastic moldings business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment

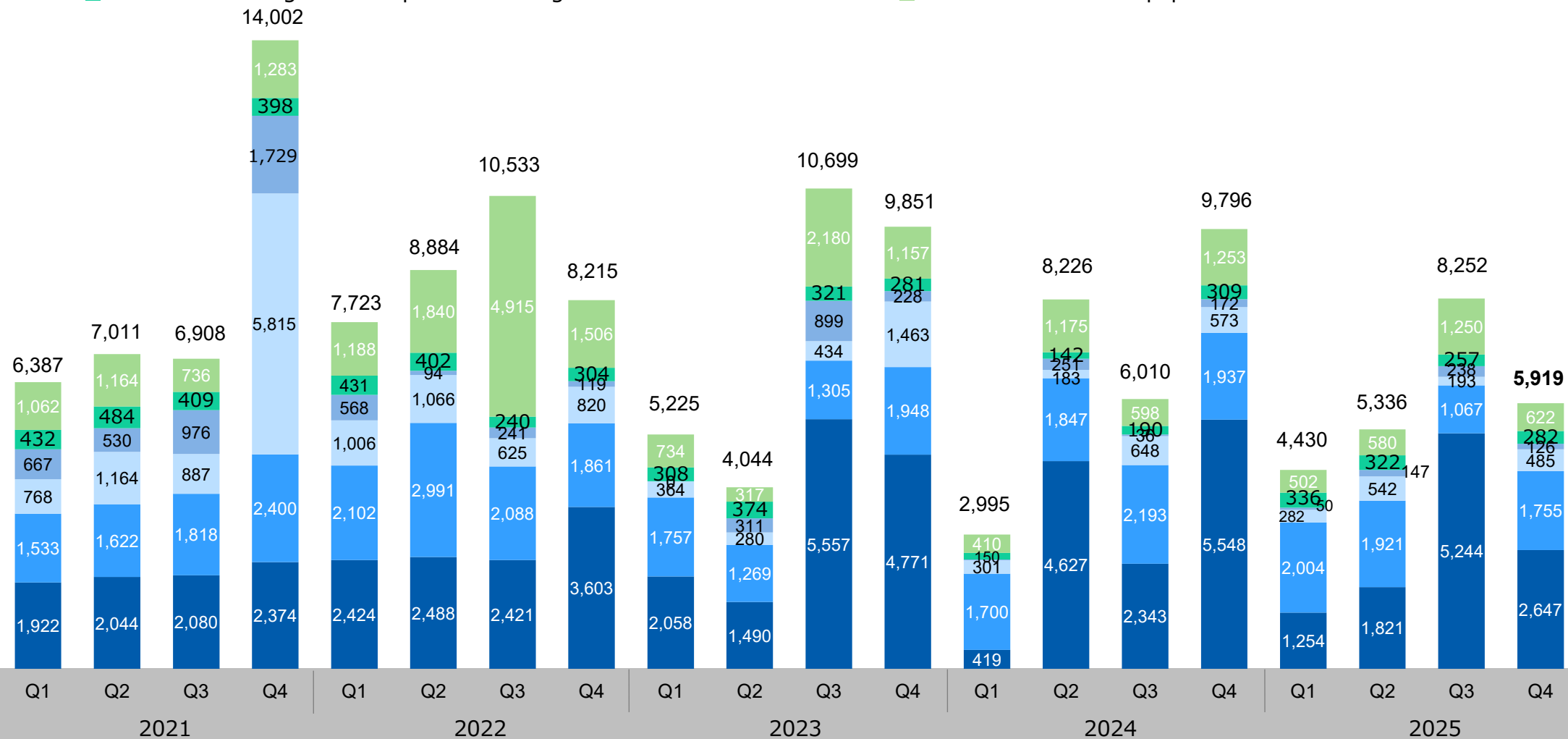
(Millions of yen)



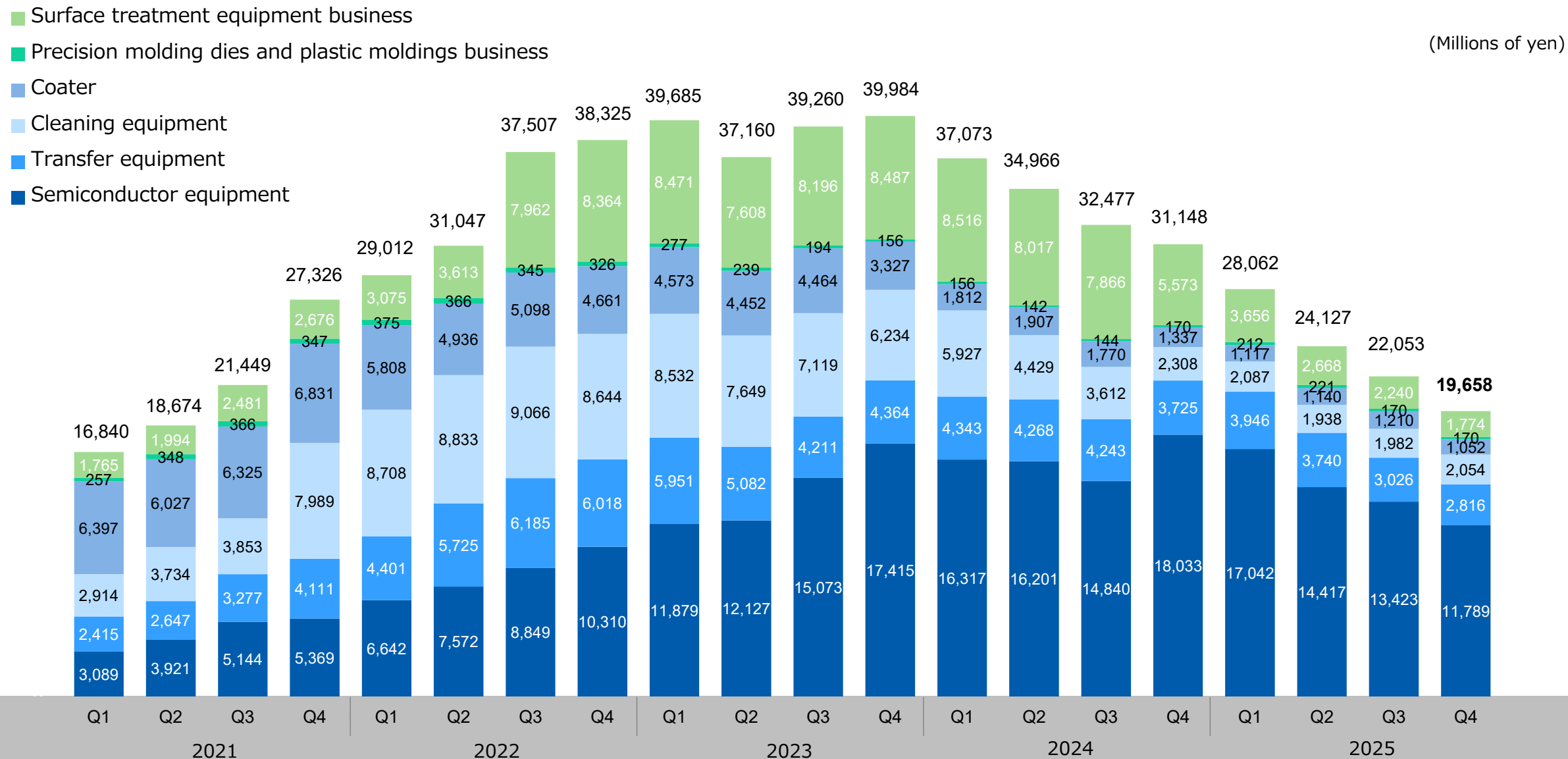
Trend in Sales Orders by Conventional Segment(Quarter)

- Semiconductor equipment
- Cleaning equipment
- Precision molding dies and plastic moldings business
- Transfer equipment
- Coater
- Surface treatment equipment business

(Millions of yen)



Trend in Order Backlog by Conventional Segment



- | | | | | | |
|------|---|--|------|---|--|
| 1972 | ● | - TAZMO Co., Ltd. is incorporated to manufacture and produce electronic components and repair industrial equipment. | 2009 | ● | - Developed 10th generation compatible full-color filter manufacturing system; production and sales started.
- Concluded a license agreement with 3M(USA) for semiconductor manufacturing equipment. |
| 1980 | ● | - Began production of molding dies, including injection molding dies.

- Completed development of Fully-automated Photo Resist Coater; production and sales started. | 2013 | ● | - Apprecia Technology Inc. became our wholly owned subsidiary company.

- VIETNAM CO., LTD. Constructed new factory at Long Hau Industrial Park in Long An Province, Vietnam. |
| 1989 | ● | - Developed TFT Full-color filter manufacturing system; production and sales started. | 2017 | ● | - Facility Co., Ltd. and Quark Technology Co., Ltd. became our wholly owned subsidiary company. |
| 1990 | ● | - Constructed new head office/plant at 6186 Kinoko-Cho, Ibara, Okayama

- Developed and produced Ultra Compact Transfer System for Super Clean Room. | 2018 | ● | - Listed on the First Section of the Tokyo Stock Exchange |
| 1994 | ● | - Began production and sales of Emboss Carrier Tape. | 2019 | ● | - Constructed a new head office at 5311 Haga Kita-ku, Okayama-shi, Okayama |
| 1995 | ● | - Began production of injection Molding Products. | 2020 | ● | - Merged with Apprecia Technology Inc. |
| 2001 | ● | - Developed "CS13" series Photo Resist Coater specialized for a thicker film application; production and sales started. | 2022 | ● | - TAZMO's listing transferred to Prime Market in Tokyo Stock Exchange.

- Increased capital to 3,495,400,000 yen through public offering.

- Established TAZMO SEMITEC SHAOXING TECHNOLOGY Co., Ltd. a consolidated subsidiary, in Zhejiang Shaoxing, China. |
| 2004 | ● | - Listed on the JASDAQ market. | | | |
| 2008 | ● | - Established TAZMO VIETNAM CO., LTD. a consolidated subsidiary, in Ho Chi Minh City, Vietnam. | | | |

Semiconductor Manufacturing Equipment Business Unit

Bonder / Debonder

- For Advanced Packaging(WLP *1 / PLP *2)
- For Power Semiconductors



We develop, design, manufacture, and sell temporary bonding and debonding systems that enable wafer thinning, an essential process for the production of high-performance chips. By bonding wafers to glass carrier substrates, our systems allow wafer thinning while preventing damage to the wafers.

Coater / Developer

Leveraging the expertise gained through the development and manufacturing of FPD production equipment, we enable uniform chemical coating and precise circuit formation by selectively removing only the exposed areas during the development process.

*1 WLP: Wafer-Level Packaging

*2 PLP : Panel-Level Packaging

Transfer Business Unit

- For Semiconductor Equipment Manufacturers (Wafers, Masks, and Related Components)



Cleaner Business Unit

We develop, design, manufacture, and sell single-wafer cleaning systems for wafer manufacturers, as well as slurry supply systems and equipment that recovers and reuses phosphoric acid from waste liquids.

Molding Business

We provide precision molds and resin molded products for connector manufacturers.

Surface Treatment Business

We provide plating systems for printed circuit boards used in semiconductor packages and electronic control systems for automobiles and other applications.

Notes

Forward-looking statements with respect to TAZMO's business plan, prospects and other such information are based on information available at the time of publication. Actual performance and results may differ significantly from the business plan described here due to changes in various external and internal factors.

This material takes as its objective the provision of information regarding the management policy, plans, and financial situation of TAZMO to shareholders, investors and other visitors. It constitutes neither an offer nor a solicitation to purchase or sell TAZMO stock.

Contact

**Finance Department,
Investor Relations Section
TAZMO CO., LTD.**



keiki@tazmo.co.jp